

# E1.S 4TG2-P series



Diagram 5.9mm (512GB-4TB)

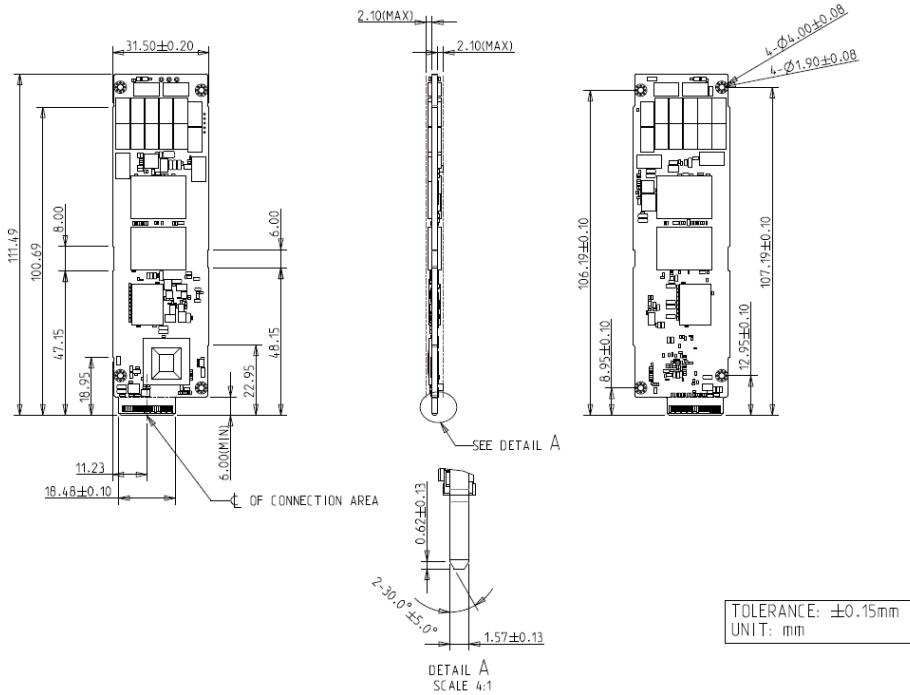


Diagram 5.9mm (8TB)

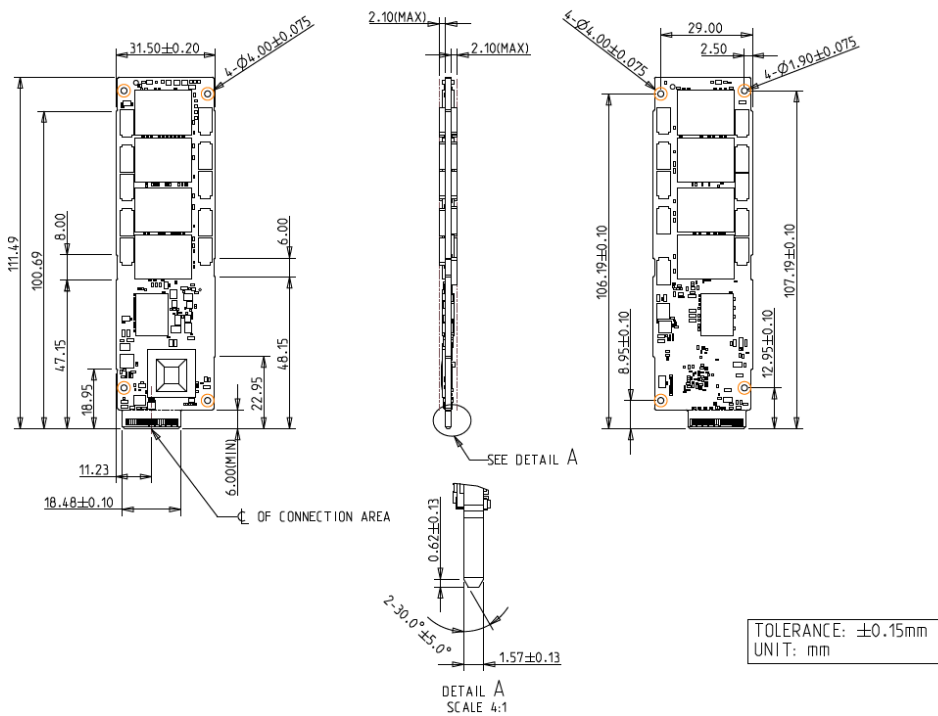


Diagram 9.5mm enclosure

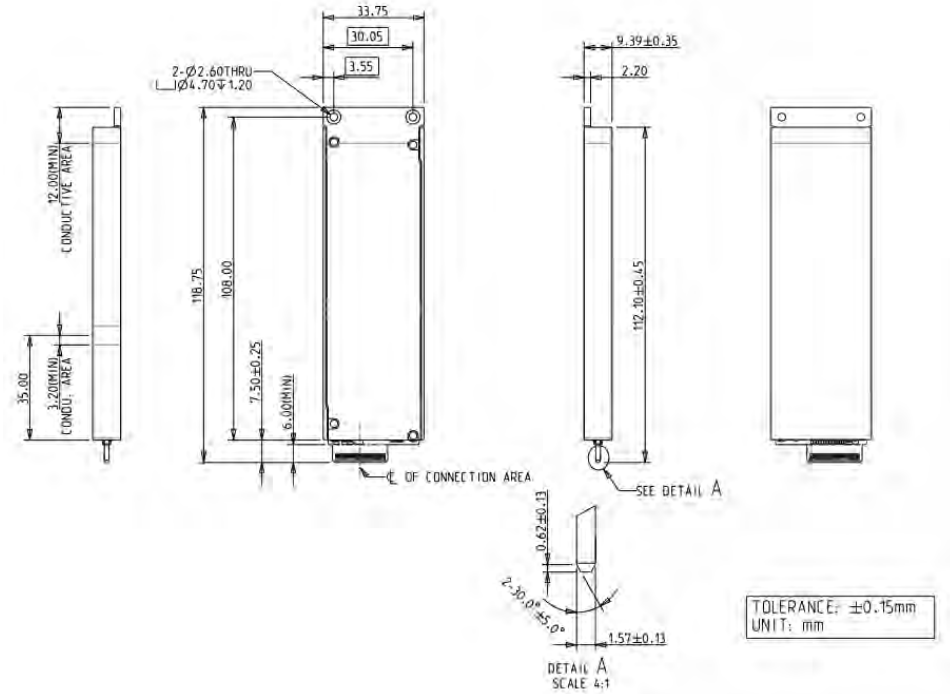
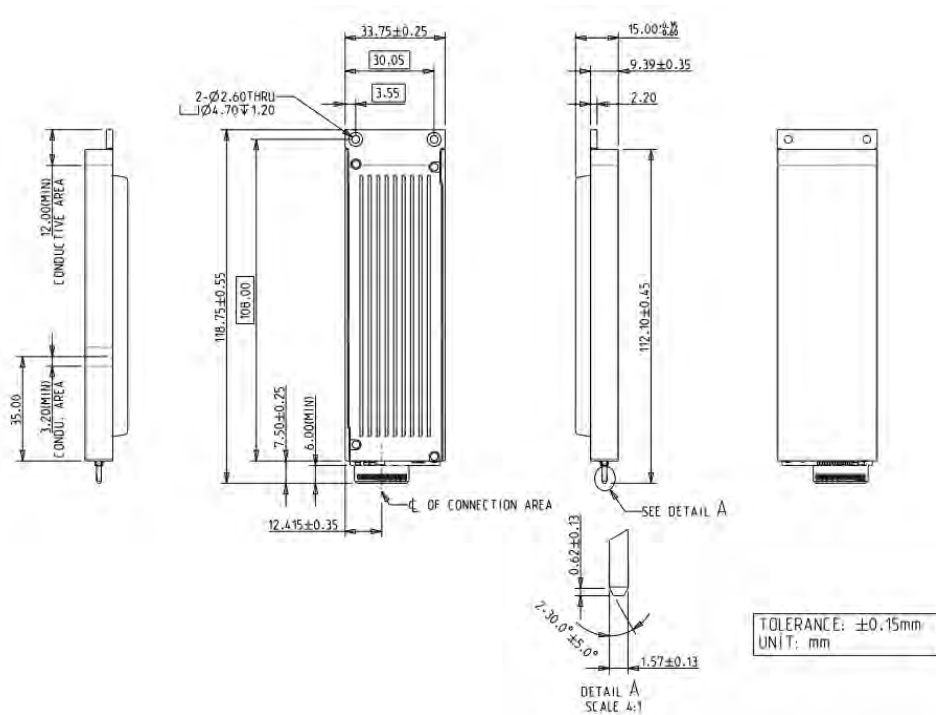


Diagram 15mm enclosure



## Specifications

Interface	PCIe Gen. 4x4
Flash Type	3D TLC
P/E cycle	3,000
Capacity	512GB~8TB
Max. Channels	8
Sequential R/W (MB/sec, max.)	6,900/4,700
Max. Power Consumption	12W
Thermal Sensor	√
External DRAM buffer	√
TCG Opal	√
H/W Write Protect	NA
Dimension (WxLxH)	5.9mm: 31.5 X 111.5 X 5.9 mm 9.5mm: 33.75 X 118.75 X 9.5 mm 15mm: 33.75 X 118.75 X 15 mm
Environment	Vibration: 20G @7~2000Hz Shock: 1500G @ 0.5ms Storage Temperature: -40°C ~ +85°C MTBF: 3 million hours

## Ordering Information

Operation Temp.	512GB	1TB	2TB	4TB	8TB
Standard Grade (0°C ~ +70°C)	DGE1S- C12DP2KCAEFP%	DGE1S- 01TDP2KCAEFP%	DGE1S- 02TDP2KCAEFP%	DGE1S- 04TDP2KCAEFP%	DGE1S- 08TDP2KCBEP%
Industrial Grade (-40°C ~ +85°C)	DGE1S- C12DP2KWAEFP%	DGE1S- 01TDP2KWAEFP%	DGE1S- 02TDP2KWAEFP%	DGE1S- 04TDP2KWAEFP%	DGE1S- 08TDP2KWBEFP%

Operation temperature based on temperature obtained from S.M.A.R.T.

?: Non-existent=5.9mm; H=9.5mm enclosure; H1=15mm enclosure

E1.S 4TG2-P specifications are subject to change.